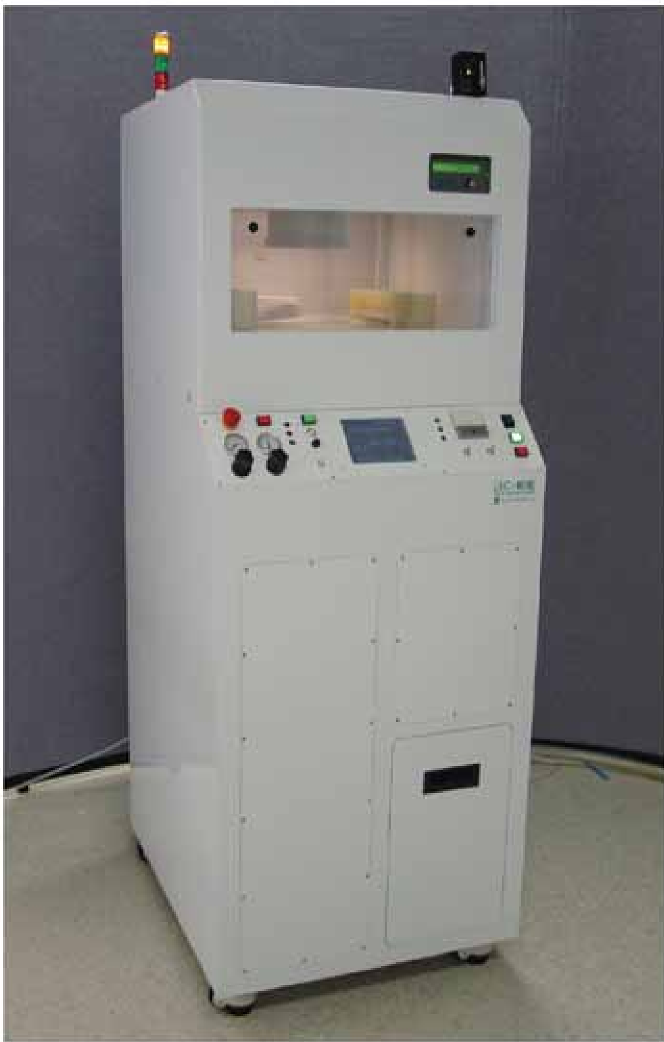
LSC-4000 Cleaning and Processing Technology



Applications:

Cleaning

- Wafers
- Chips on Wafer Frame
- Display Panels
- ITO Coated Displays
- Patterned and Un-patterned Masks
- Mask Blanks
- Pelliclized Masks
- Contact Masks

Photoresist Processing

- Piranha Stripping
- Resist Coating
- Lift-Off

Etching

- Al, Au, Cr, Ti

Features:

- 21" OD, 15"x15" Substrates
- Large Environmental Chamber with Megasonic DI, Brush, Hot DI, High Pressure DI, Heated N_2, Chemical Dispense Arm
- Variable Speed Brush with Chemical Dispense
- Touchscreen User Interface
- Manual Load and Unload
- Safety Interlocks and Alarm
- 30"D x 26"W Footprint

Options:

- Chemical Delivery Module
- Piranha Cleaning
- Ozone Generator
- Hydrogenated DI Water Generator
- High Pressure DI Module
- Sulphuric Acid Hydrogen Peroxide
- IR Heating
- DI Water Recirculator
- Robotic Load Unload Module

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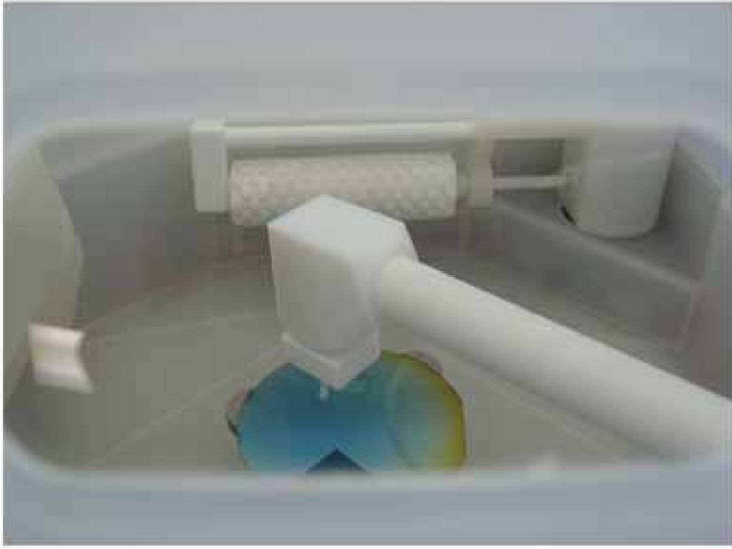
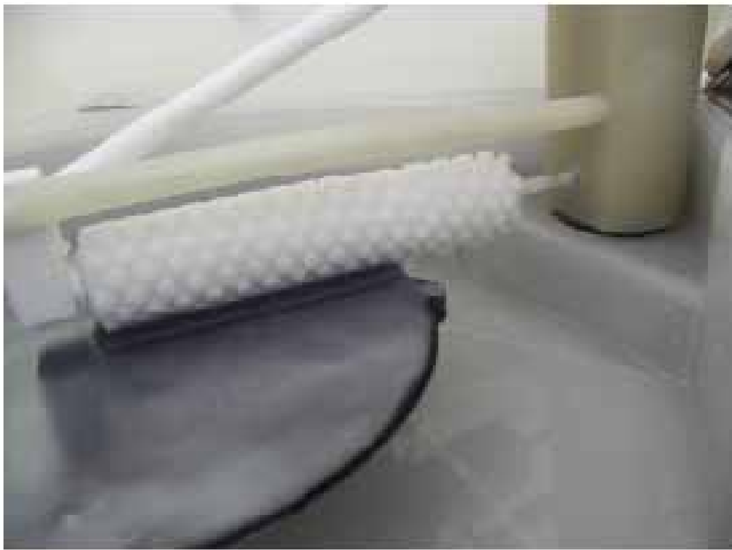


Piranha Cleaning

- H_2SO_4 and H_2O_2 Dispensed and Mixed on the Wafer
- IR Heating
- Brush Clean
- Megasonic DI Water Clean
- Heated N_2 and Spin Dry

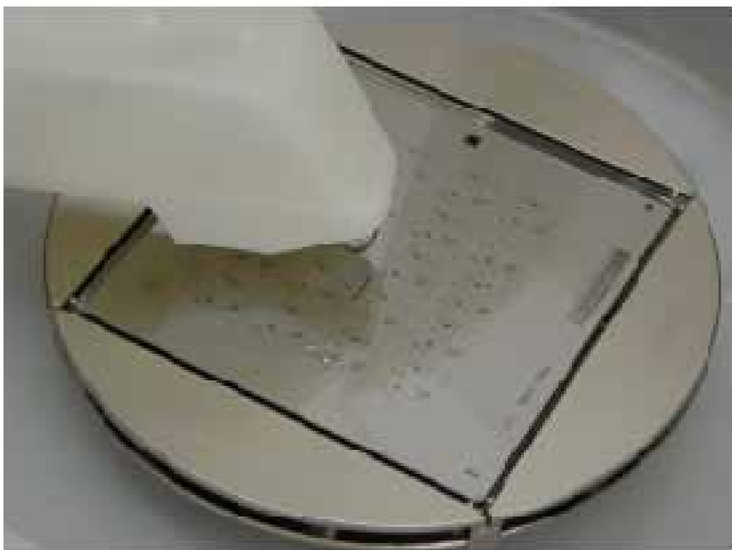
Resist Stripping / Lift Off

- NMP Dispense with IR Heating
- Brush Clean
- Megasonic DI Water Clean
- Heated N_2 and Spin Dry



CMP Wafer Cleaning

- Removes CMP Particles with Brush and Megasonic DI Cleaning
- Chemical Dispense Arm
- Chemical Dispense Canisters
- Special Chucks for Front Side and Back Side Brush Cleaning
- Variable Speed PVA Brush
- Adjustable Brush/Wafer Contact Pressure
- Chemical Dispense Through Brush



Pelliclized/Unpelliclized Mask Cleaning

- Full Cleaning without Necessity of Pellicle Replacement
- Pellicle is Fully Protected
- Pelliclized Mask Cleaning Process:

1) Back Side of the Mask is Cleaned:
   Megasonic DI Clean
   Brush Clean
   Chemical Clean
   Heated N_2 Spin Dry
2) Front Side Alignment Marks Cleaned:
   Megasonic DI Clean
   Light Chemical Clean
3) Heated N_2 Spin Dry